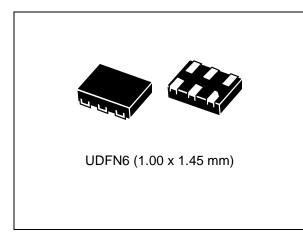


SR1

4 pin Smart Reset™

Datasheet - production data



ApplicationsWearable

- Activity tracker
- Smartwatch
- Smartglasses

Features

- Operating voltage range 2 V to 5.5 V
- Low supply current 1 μA
- Integrated test mode
- Single Smart Reset[™] push-button input with fixed extended reset setup delay (t_{SRC}) from 0.5 s to 10 s in 0.5 s steps (typ.), option with internal input pull-up resistor
- Push-button controlled reset pulse duration
 - Option 1: fully push-button controlled, no fixed or minimum pulse width guaranteed
 - Option 2: defined output reset pulse duration (t_{REC}), factory-programmed
- Single reset output
 - Active low or active high
 - Push-pull or open drain with optional pullup resistor
- Fixed Smart Reset input logic voltage levels
- Operating temperature: -40 °C to +85 °C
- UDFN6 package 1.00 mm x 1.45 mm

This is information on a product in full production.

 ECOPACK[®]2 (RoHS compliant, Halogen-Free)

Contents

1	Desci	ription	3
	1.1	Test mode	3
	1.2	Logic diagram	4
	1.3	Pin connections	4
2	Devic	e overview	5
3	Pin de	escriptions	6
	3.1	Power supply (V _{CC})	6
	3.2	Power-up sequence	6
	3.3	Ground (V _{SS})	6
	3.4	Smart Reset input (SR)	6
	3.5	Reset output (RST)	6
	3.6	RST output undervoltage behavior (for open-drain option)	6
4	Туріс	al application diagrams	7
5	Timin	g diagrams	9
6	Туріс	al operating characteristics10	D
7	Maxir	num ratings	2
8	DC ar	nd AC parameters	3
9	Packa	age information	5
10	Таре	and reel information 17	7
			_
11	Part r	numbering	8
11 12		numbering	



1 Description

The Smart ResetTM devices provide a useful feature which ensures that inadvertent short reset push-button closures do not cause system resets. This is done by implementing an extended Smart Reset input delay time (t_{SRC}), which ensures a safe reset and eliminates the need for a specific dedicated reset button.

This reset configuration provides versatility and allows the application to distinguish between a software generated interrupt and a hard system reset. When the input push-button is connected to the microcontroller interrupt input, and is closed for a short time, the processor can only be interrupted. If the system still does not respond properly, continuing to keep the push-button closed for the extended setup time t_{SRC} causes a hard reset of the processor through the reset output.

The SR1 has one Smart Reset input (\overline{SR}) with preset delayed Smart Reset setup time (t_{SRC}). The reset output (\overline{RST}) is asserted after the Smart Reset input is held active for the selected t_{SRC} delay time. The RST output remains asserted either until the \overline{SR} input goes to inactive logic level (i.e. neither fixed nor minimum reset pulse width is set) or the output reset pulse duration is fixed for t_{REC} (i.e. factory-programmed). The device fully operates over a broad V_{CC} range from 2.0 V to 5.5 V.

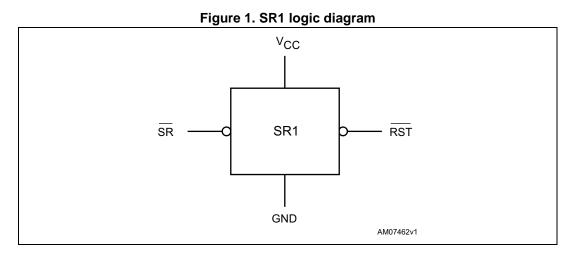
1.1 Test mode

After pulling SR up to V_{TEST} (V_{CC} + 1.4 V) or above, the counter starts to count the initial shortened t_{SRC-INI} (42 ms, typ.). After t_{SRC-INI} expires, the RST output either goes down for t_{REC} (if t_{REC} option is used) or stays low as long as overvoltage on SR is detected (if t_{REC} option is not used). This is feedback, and the user only knows that the device is locked in test mode. Each time the SR input is connected to ground in test mode, a shortened t_{SRC-SHORT} (t_{SRC}/128) is used instead of regular t_{SRC} (0.5 s - 10 s). In this way the device can be quickly tested without repeating test mode triggering. Return to normal mode is possible by performing a new startup of the device (i.e. V_{CC} goes to 0 V and back to its original state).

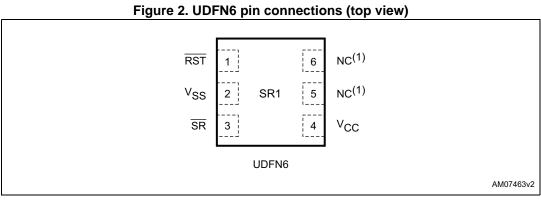
The advantages of this solution are its high glitch immunity, user feedback regarding entry into test mode, and testability within the full V_{CC} range.



1.2 Logic diagram



1.3 Pin connections



1. Not connected (not bonded); should be connected to V_{SS} .

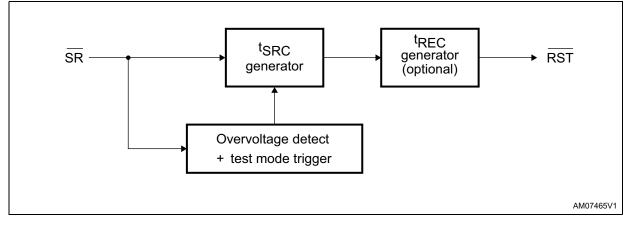


2 Device overview

Pin n°	n° Name Type Description							
1	RST	Output	Reset output, active low, open drain.					
2	V _{SS}	Supply ground	Ground					
3	SR	Input	Smart Reset input, active low.					
4	V _{CC}	Supply voltage	Positive supply voltage for the device. A 0.1 μF decoupling ceramic capacitor is recommended to be connected between V_{CC} and V_{SS} pins.					
5	NC	-	Not connected (not bonded); should be connected to $V_{\text{SS}}.$					
6	NC	-	Not connected (not bonded); should be connected to $V_{\text{SS}}.$					

Table	1	Signal	names
Table		Jigilai	names

Figure 3. SR1 block diagram





3 Pin descriptions

3.1 Power supply (V_{CC})

This pin is used to provide power to the Smart Reset device. A 0.1 μF ceramic decoupling capacitor is recommended to be connected between the V_{CC} and V_{SS} pins, as close to the SR1 device as possible.

3.2 Power-up sequence

In normal mode, if different input side (\overline{SR}) and V_{CC} voltage domains are used, power-on sequence must avoid meeting the test mode entry condition to avoid inadvertent test mode entry: there should not be logic high present on the \overline{SR} input before the V_{CC} power-up. However V_{CC} and V(\overline{SR}) rising at the same time is OK (e.g. if both are in the same voltage domain), the device will then safely start into normal operating mode, with \overline{RST} output inactive (in High-Z mode for open-drain option).

3.3 Ground (V_{SS})

This is the ground pin for the device.

3.4 Smart Reset input (SR)

Push-button Smart Reset input, active low with optional <u>pull-up</u> resistor. SR input needs to be asserted for at least t_{SRC} to assert the reset output (RST).

By connecting a voltage higher than V_{CC} + 1.4 V to the \overline{SR} input the device enters test mode (see Section 1: Description on page 3 for more information).

3.5 Reset output (RST)

RST is active low or active high, open drain or push-pull reset output with optional internal pull-up resistor.

Output reset pulse width is optional as follows:

- Neither fixed nor minimum output reset pulse duration (releasing the push-button while reset output is active, causes the output to de-assert)
- Fixed, factory-programmed output reset pulse duration for t_{REC} independent on Smart Reset input state.

3.6 RST output undervoltage behavior (for open-drain option)

High-Z on RST output below the specified operating voltage range is guaranteed at V_{CC} power-on or in case that valid V_{CC} dropped while the device was idle, i.e. while both output and input were inactive.



4 Typical application diagrams

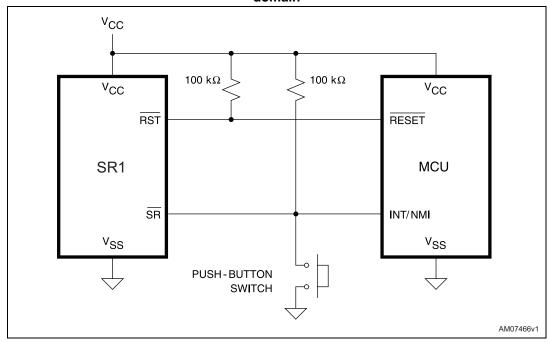
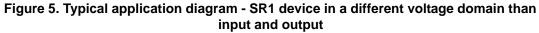
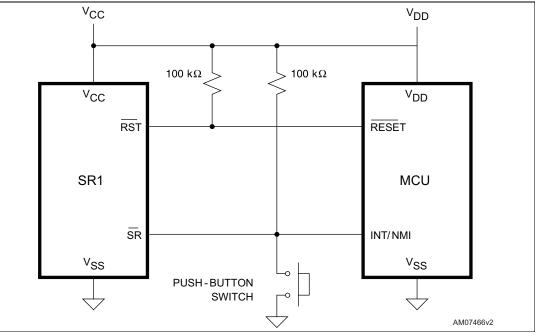


Figure 4. Typical application diagram - input, output and SR1 device in one voltage domain





 Open-drain RST output type and fixed SR input logic threshold allows to use the device in different voltage domains. To prevent entering test mode by creating a condition V(SR) > V_{CC} + 1.1 V typ., V_{CC} should be powered up before or together with voltage on the SR input.



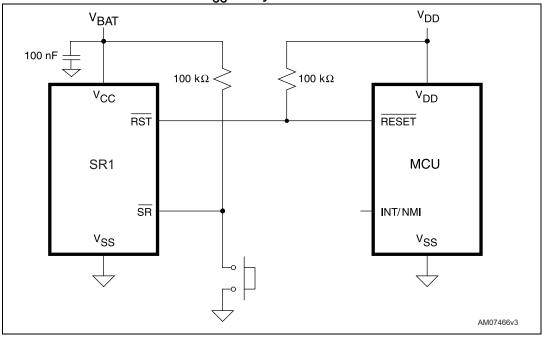


Figure 6. Typical application diagram in different voltage domains - SR input in V_{BAT} domain like V_{CC} totally disables the test mode



5 Timing diagrams

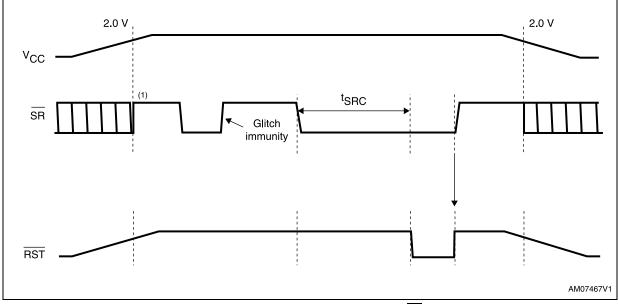
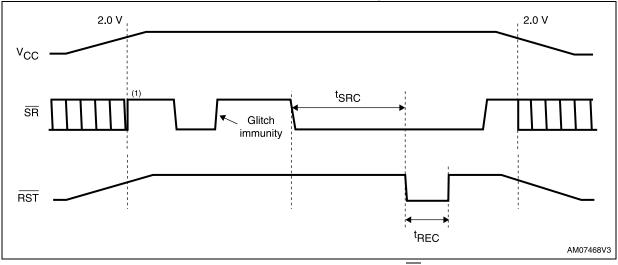


Figure 7. RST output without t_{REC} option

1. V_{CC} should be powered up before or together with voltage on the \overline{SR} input to prevent entering test mode by creating a condition $V(\overline{SR}) > V_{CC} + 1.1 V$ typ.

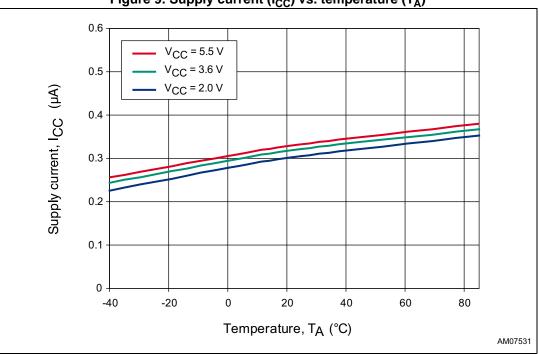


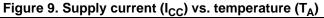


 V_{CC} should be powered up before or together with voltage on the SR input to prevent entering test mode by creating a condition V(SR) > V_{CC} +1.1 V typ.

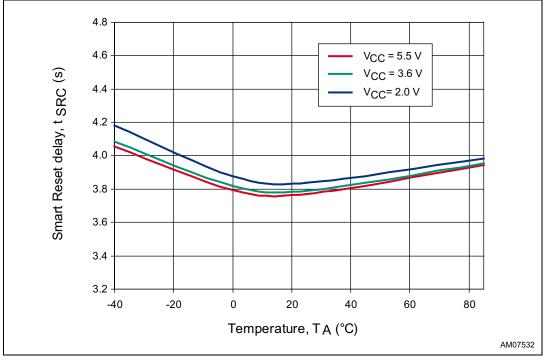


6 Typical operating characteristics











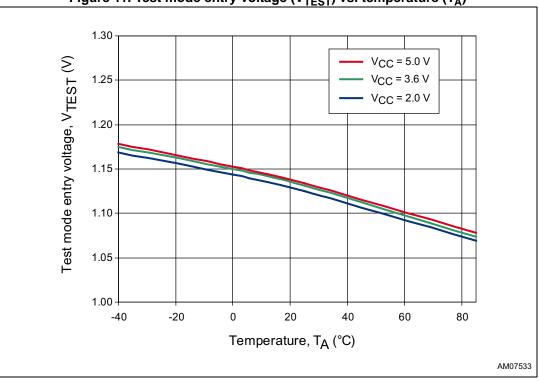


Figure 11. Test mode entry voltage (V_{TEST}) vs. temperature (T_A)

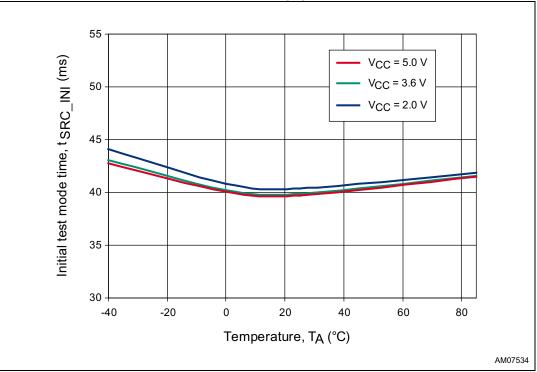


Figure 12. Initial test mode time $(t_{SRC-INI})$ vs. temperature (T_A)



DocID026048 Rev 2

7 Maximum ratings

Stressing the device above the rating listed in *Table 2: Absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in *Table 3: Operating and measurement conditions* of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics[™] SURE program and other relevant quality documents.

Symbol	Parameter	Value	Unit
T _{STG}	Storage temperature (V _{CC} off)	-55 to +150	°C
T _{SLD} ⁽¹⁾	Lead solder temperature for 10 seconds	260	°C
V _{IO}	Input or output voltage	-0.3 to 5.5	V
V _{CC}	Supply voltage	-0.3 to 7	V
ESD			
V _{HBM}	Electrostatic discharge protection, human body model (JESD22- A114-B level 2)	2	kV
V _{RCDM}	Electrostatic discharge protection, charged device model, all pins	1	kV
V _{MM}	Electrostatic discharge protection, machine model, all pins (JESD22-A115-A level A)	200	V
	Latch-up (V _{CC} pin, SR reset input pin)	EIA/JESD78	

Table :	2. /	Absolute	maximum	ratings
---------	------	----------	---------	---------

1. Reflow at peak temperature of 260 °C. The time above 255 °C must not exceed 30 seconds.



8 DC and AC parameters

This section summarizes the operating measurement conditions, and the DC and AC characteristics of the device. The parameters in *Table 4: DC and AC characteristics* are derived from tests performed under the measurement conditions summarized in *Table 3: Operating and measurement conditions*. Designers should check that the operating conditions in their circuit match the operating conditions when relying on the quoted parameters.

Symbol	Parameter	Value	Unit
V _{CC}	Supply voltage	2.0 to 5.5	V
T _A	Ambient operating temperature	-40 to +85	°C
t _R , t _F	Input rise and fall times	≤ 5	ns
	Input pulse voltages	0.2 to 0.8 V _{CC}	V
	Input and output timing reference voltages	0.3 to 0.7 $\rm V_{CC}$	V



Symbol	Parameter	Test conditions ⁽¹⁾	Min.	Тур. ⁽²⁾	Max.	Unit
V _{CC}	Supply voltage		2.0		5.5	V
I _{CC}	Supply current	$\overline{SR} = V_{CC}$, t_{REC} and t_{SRC} counter is not running		0.4	1.0	μA
		$V_{CC} \ge 4.5 \text{ V}$, sinking 3.2 mA			0.3	V
V _{OL}	Reset output voltage low	$V_{CC} \ge 3.3 \text{ V}$, sinking 2.5 mA			0.3	V
		$V_{CC} \ge 2.0 \text{ V}$, sinking 1 mA			0.3	V
t	Reset timeout delay,	(device option)	140	210	280	ms
t _{REC}	factory-programmed		240	360	480	ms
R _{PUO}	Internal out <u>put p</u> ull-up resistor on RST	(device option)		65		kΩ
I _{LO}	Output leakage current	$V_{\overline{RST}} = 5.5 V$, open drain device option without output pull-up resistor	-0.1		0.1	μA
Smart Rese	t					
	Smart Depart delay	T _A = -40 to +85 °C	0.8 x t _{SRC}	↓ (3)	1.2 x t _{SRC}	s
t _{SRC}	Smart Reset delay	T _A = 25 °C	0.9 x t _{SRC}	t _{SRC} ⁽³⁾	1.1 x t _{SRC}	
V _{IL}	SR input voltage low		V _{SS} -0.3		0.3	V
V _{IH}	SR input voltage high		0.85		5.5	V
R _{PUI}	Internal inp <u>ut p</u> ull-up resistor on SR	(device option)		65		kΩ
I _{LEAK}	SR input leakage current	device option without input pull-up resistor	-0.1		0.1	μA
	Input glitch immunity			t _{SRC}		s
Fest mode						
V _{TEST}	Test mode entry voltage		V _{CC} +0.9	V _{CC} +1.1	V _{CC} +1.4	V
t _{SRC-INI}	Initial test mode time		28	42	56	ms
t _{SRC-SHORT}	Shortened Smart Reset delay			t _{SRC} / 128		ms

1. Valid for ambient operating temperature T_A = -40 to +85 °C, V_{CC} = 2.0 to 5.5 V.

2. Typical values are at 25 °C and V_{CC} = 3.3 V unless otherwise noted.

3. Factory-programmable in the range of 0.5 s to 10 s typ. in 0.5 s steps.



9 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK is an ST trademark.

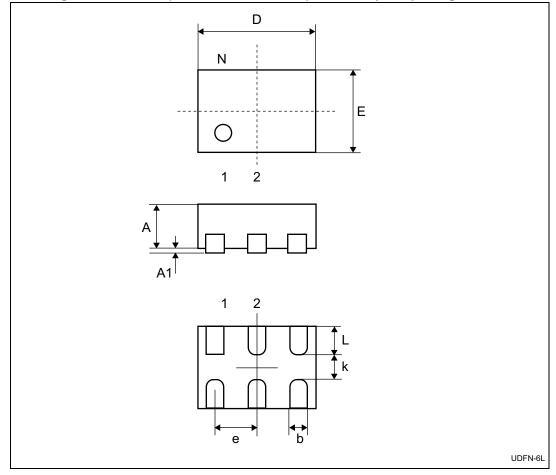


Figure 13. UDFN6, (1.00 x 1.45 x 0.50 mm), 0.50 mm pitch package outline

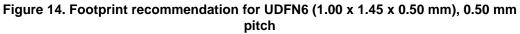


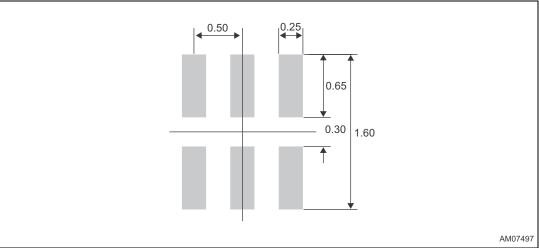
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	Dimensions						
Symbol	(mm) (inches)						Note ⁽¹⁾
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	0.50	0.55	0.60	0.0197	0.0217	0.0236	
A1	0.00	0.02	0.05	0.000	0.0008	0.0020	
b	0.18	0.25	0.30	0.0071	0.0098	0.0118	
D	1.40	1.45	1.50	0.0551	0.0571	0.0591	
E	0.95	1.00	1.05	0.0374	0.0394	0.0413	
е	0.45	0.50	0.55	0.0177	0.0197	0.0217	
k	0.20			0.0079			
L	0.30	0.35	0.40	0.0118	0.0138	0.0157	

Table 5. UDFN6, (1.00 x 1.45 x 0.50 mm), 0.50 mm pitch package mechanical data

1. Package outline exclusive of any mold flashes dimensions and metal burrs.







10 Tape and reel information

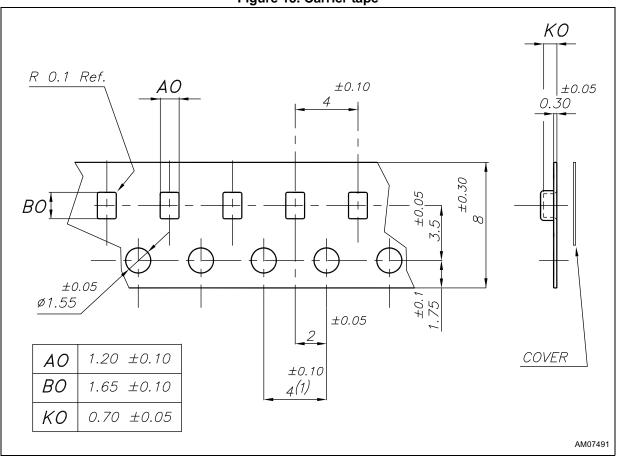
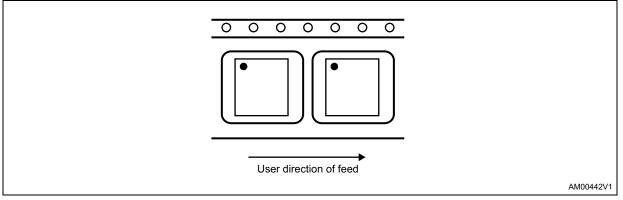


Figure 15. Carrier tape

1. 10-sprocket hole pitch cumulative tolerance ± 0.20 .

Figure 16. Pin 1 orientation





11 Part numbering

Example:	SR1	н	Α	R	ι
Device type					
SR1					
Smart Reset setup	o delay (t _{SRC}) ⁽¹⁾				
C = factory program	nmable t _{SRC} = 1.5 s (typ.)				
H = factory program	nmable t _{SRC} = 4.0 s (typ.)				
L = factory program	mable t _{SRC} = 6.0 s (typ.)				
P = factory program	nmable t _{SRC} = 7.5 s (typ.)				
	nmable t _{SRC} = 10.0 s (typ.)				
Inputs, outputs ty A = active low SR in active low open dra B = active low SR in	pe ⁽²⁾ nput with no pull-up, in RST output with no pull-up nput with pull-up,				
Inputs, outputs ty A = active low SR in active low open dra B = active low SR in	pe ⁽²⁾ nput with no pull-up, in RST output with no pull-up nput with pull-up, in RST output with no pull-up				
Inputs, outputs ty A = active low SR ii active low open dra B = active low SR ii active low open dra Reset timeout per A = factory program	pe(2) hput with no pull-up, in RST output with no pull-up hput with pull-up, in RST output with no pull-up iod (t _{REC}) hmable t _{REC} = 210 ms (typ.)				
Inputs, outputs ty A = active low SR in active low open dra B = active low SR in active low open dra Reset timeout per A = factory program B = factory program	pe(2) hput with no pull-up, in RST output with no pull-up hput with pull-up, in RST output with no pull-up iod (t_{REC}) hmable t _{REC} = 210 ms (typ.) hmable t _{REC} = 360 ms (typ.)				
Inputs, outputs ty A = active low SR in active low open dra B = active low SR in active low open dra Reset timeout per A = factory program B = factory program	pe(2) hput with no pull-up, in RST output with no pull-up hput with pull-up, in RST output with no pull-up iod (t _{REC}) hmable t _{REC} = 210 ms (typ.)				

- Smart Reset delay (t_{SRC}) is available from 0.5 s to 10 s in 0.5 s steps (typ.). Minimum order quantities may apply. Contact local sales office for availability.
- Push-pull reset output type also available (active low or active high). SR input and open drain reset output available with optional pull-up resistor. Minimum order quantities may apply. Contact local sales office for availability.



12 Package marking information

Part number	t _{SRC} (s)	Smart Reset inputs ⁽¹⁾	Output type ⁽²⁾	t _{REC} option ⁽³⁾	Package	Topmark			
SR1CARU	1.5	AL	OD, AL	No t _{REC}	UDFN6	CA			
SR1HARU	4.0	AL	OD, AL	No t _{REC}	UDFN6	HA			
SR1LARU	6.0	AL	OD, AL	No t _{REC}	UDFN6	LA			
SR1PAAU	7.5	AL	OD, AL	210 ms	UDFN6	PB			
SR1PARU	7.5	AL	OD, AL	No t _{REC}	UDFN6	PA			
SR1PBBU	7.5	AL + pull-up	OD, AL	360 ms	UDFN6	PC			
SR1UARU	10.0	AL	OD, AL	No t _{REC}	UDFN6	UA			

Table 7. Package marking

1. AL = active low.

2. OD = open drain, AL = active low.

3. No t_{REC} = push-button controlled reset pulse width, any other value represents typical value of t_{REC} .

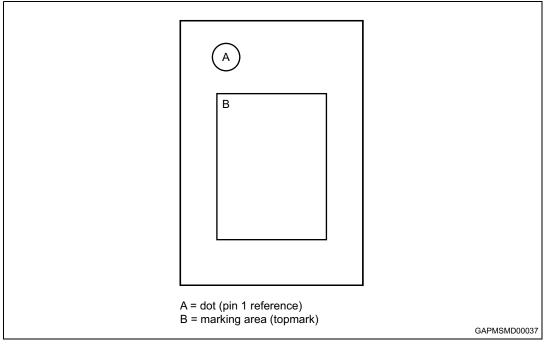


Figure 17. Package marking (top view)



13 **Revision history**

Та	able 8.	Document	revision	history	

Date	Revision	Changes
10-Mar-2014	1	Initial release
13-May-2014	2	Modified t _{REC} values <i>Table 4 on page 14</i>



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